

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1-12. (Canceled)

13. (Previously presented) A method of EMI shielding a circuit board or flexible circuitry, the method comprising:

encapsulating a portion of the circuit board or flexible circuitry so that more than at least one electronic component is encapsulated with a conforming insulating base coating;

vacuum metallizing a first conductive layer over the insulating base coating
encapsulating the portion of the circuit board or flexible circuitry; and

grounding the first conductive layer to a ground trace to provide a grounded EMI shield for the encapsulated electronic component.

14. (Canceled)

15. (Previously presented) The method of claim 13 further comprising maintaining a temperature of the electronic component and insulating base coating below approximately 200°C during vacuum metallizing.

16. (Original) The method of claim 13 wherein the first conductive layer comprises aluminum, copper, silver, gold, tin, or nickel-chromium.

17. (Original) The method of claim 13 further comprising applying a second conductive layer over the first conductive layer

18. (Original) The method of claim 13 further comprising applying an insulating conformal layer over the first conductive layer.

19. (Original) The method of claim 18 wherein the conformal layer is waterproof.

20. (Previously presented) The method of claim 13 further comprising improving the adhesion between the conforming insulating base coating and the first conductive layer by using a glow discharge process.

21. (Original) The method of claim 13 further comprising positioning the ground trace around a periphery of the component.

22. (Previously presented) The method of claim 13 wherein the at least one electronic component comprises a first and second component, wherein the ground trace is disposed between the first and second component.

23. (Original) The method of claim 13 further comprising exposing the ground trace through the insulating coating.

24.-72. (Canceled)

73. (New) The method of claim 13 further comprising improving the adhesion between the conforming insulating base coating and the first conductive layer by using a glow discharge process in which the polymer substrate is bombarded with electrons and negative ions of inert or reactive gasses to treat the surface.

74. (New) The method of claim 73 wherein the inert gasses are selected from the group consisting of argon and nitrogen and the reactive gasses are selected from the group consisting of oxygen, nitrous oxide, fluoride containing compounds, and chlorine containing compounds.

75. (New) A method of EMI shielding a circuit board or flexible circuitry, the method comprising:

- forming a peripheral dam under a ground trace for holding an insulating base coat within the substrate during manufacture;

- encapsulating a portion of the circuit board or flexible circuitry so that more than one electronic component is encapsulated with the insulating base coating and the insulating base coating conforms to the shape of the encapsulated portion of the circuit board or flexible circuitry;

- vacuum metallizing a first conductive layer over the insulating base coating encapsulating the portion of the circuit board or flexible circuitry; and

- grounding the first conductive layer to a ground trace to provide a grounded EMI shield for the encapsulated electronic components.

76. (New) A method of EMI shielding a circuit board or flexible circuitry, the method comprising:

- encapsulating a substantial portion of the circuit board or flexible circuitry so that all of the electronic components are encapsulated with a conforming insulating base coating;

- vacuum metallizing a first conductive layer over the insulating base coating encapsulating the substantial portion of the circuit board or flexible circuitry; and

- grounding the first conductive layer to a ground trace to provide a grounded EMI shield for the encapsulated electronic components.